

L Number	Hits	Search Text	DB	Time stamp
1	1561	(chip die IC) and (lead adj frame) and solder and (heat adj (sink plate slug element spreader dissipat\$4)) and solder	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT	2004/02/27 12:58
2	7	("4063984" "5300627" "5508357" "5510425" "5851616" "5866250" "5891540").PN.	USPAT	2004/02/27 11:39
3	7	("4063984" "5300627" "5508357" "5510425" "5851616" "5866250" "5891540").PN.	USPAT	2004/02/27 11:39
4	2	("5367196").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT	2004/02/27 11:45
5	28	("3770600" "3784440" "4092697" "4121980" "4461924" "4589010" "4640625" "4707724" "4713150" "4766095" "4767674" "4888449" "4926242" "4939316" "4994314" "5013871" "5015803" "5023398" "5038940" "5055967" "5066368" "5073521" "5098796" "5098864" "5122858" "5124783" "5155299" "5181969").PN.	USPAT	2004/02/27 11:45
6	11	("4862245" "4984059" "5184208" "5252853" "5286679" "5304842" "5440169" "5441684" "5461255" "5598034" "5604376").PN.	USPAT	2004/02/27 12:06
7	11	("4862245" "4984059" "5184208" "5252853" "5286679" "5304842" "5440169" "5441684" "5461255" "5598034" "5604376").PN.	USPAT	2004/02/27 12:19
8	11	("4862245" "4984059" "5184208" "5252853" "5286679" "5304842" "5440169" "5441684" "5461255" "5598034" "5604376").PN.	USPAT	2004/02/27 12:19
9	9	("4663833" "4672418" "4672421" "4723156" "4727221" "4784974" "4926242" "4994897" "5105259").PN.	USPAT	2004/02/27 12:21
10	11	("4862245" "4984059" "5184208" "5252853" "5286679" "5304842" "5440169" "5441684" "5461255" "5598034" "5604376").PN.	USPAT	2004/02/27 12:21
11	16	(chip die IC) and (lead adj frame) and (heat adj (sink plate slug element spreader dissipat\$4)) with wider and solder	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT	2004/02/27 13:26
12	2	("5959349").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT	2004/02/27 13:26
-	52	(lead adj frame) and (chip die IC) and (metal adj block)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT	2004/02/26 17:32
-	4	("3930114" "4396936" "4594770" "5041902").PN.	USPAT	2004/02/26 17:23
-	7	("3786317" "4012765" "4012768" "4415025" "4630172" "4698663" "4712129").PN.	USPAT	2004/02/26 17:24
-	6	("3444309" "3629672" "3689683" "3729573" "3767839" "3839660").PN.	USPAT	2004/02/26 17:30

-	1979	(lead adj frame) and (chip die IC) and (heat adj sink)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/26 17:32
-	1115	(lead adj frame) and (chip die IC) and (heat adj sink) and insulat\$4	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/26 17:37
-	154	(chip die IC) and (lead adj frame) with solder and (heat adj sink) and insulat\$4	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/26 20:03
-	6	("5077595" "5699609" "5751063" "5920119" "5942797" "6018463").PN.	USPAT	2004/02/26 17:44
-	10	("3702427" "4495378" "4577056" "4939316" "4967260" "5013871" "5025114" "5034591" "5132773" "5367196").PN.	USPAT	2004/02/26 17:48
-	28	("3770600" "3784440" "4092697" "4121980" "4461924" "4589010" "4640625" "4707724" "4713150" "4766095" "4767674" "4888449" "4926242" "4939316" "4994314" "5013871" "5015803" "5023398" "5038940" "5055967" "5066368" "5073521" "5098796" "5098864" "5122858" "5124783" "5155299" "5181969").PN.	USPAT	2004/02/26 17:51
-	87	(chips dice) and (lead adj frame) with solder and (heat adj sink) and insulat\$4	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/26 18:36
-	36	(chips dice) and (lead adj frame) and (heat adj sink) with block\$4	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/26 18:46
-	7	("5057906" "5466969" "5703399" "6060772" "6066890" "6083772" "6313520").PN.	USPAT	2004/02/26 18:39
-	7	("5057906" "5466969" "5703399" "6060772" "6066890" "6083772" "6313520").PN.	USPAT	2004/02/26 18:40
-	3	("5057906" "5424250" "5466969").PN.	USPAT	2004/02/26 18:41
-	387	(chips dice) and (heat adj sink) with block\$4	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/26 19:10
-	0	toshiaki-shinohara.in.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/26 19:10
-	0	shinohara-shinohara.in.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/26 19:11
-	195	shinohara-toshiaki.in.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/26 19:28

-	2	("5041902").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT	2004/02/26 19:56
-	7	("3786317" "4012765" "4012768" "4415025" "4630172" "4698663" "4712129").PN.	USPAT	2004/02/26 19:29
-	2	("5367196").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT	2004/02/26 19:56
-	28	("3770600" "3784440" "4092697" "4121980" "4461924" "4589010" "4640625" "4707724" "4713150" "4766095" "4767674" "4888449" "4926242" "4939316" "4994314" "5013871" "5015803" "5023398" "5038940" "5055967" "5066368" "5073521" "5098796" "5098864" "5122858" "5124783" "5155299" "5181969").PN.	USPAT	2004/02/26 20:01
-	210	(chip die IC) and (lead adj frame) with solder and (heat adj sink) and (resin packag\$4 encapsul\$5)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT	2004/02/26 20:04
-	40	("3324224" "4313492" "4335781" "4480262" "4561040" "4603374" "4727455" "4740866" "4806503" "4825284" "4888449" "4897508" "4912548" "4939316" "4949219" "4961106" "4967260" "5015803" "5018005" "5023398" "5025114" "5055967" "5066368" "5073521" "5103292" "5175613" "5184211" "5189505" "5214308" "5216283" "5235209" "5256205" "5284706" "5291064" "5323292" "5324569" "5334857" "5352926" "5353193" "5380212").PN.	USPAT	2004/02/26 20:20
-	2	("5650663").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT	2004/02/27 11:13
-	39	("3676292" "3697666" "3726987" "3728177" "3740920" "3914858" "3993123" "4105861" "4149910" "4410927" "4461924" "4468293" "4480262" "4481525" "4491622" "4500605" "4515671" "4521469" "4524238" "4525422" "4532222" "4542259" "4551210" "4552206" "4570337" "4577056" "4582556" "4594770" "4607276" "4649083" "4651192" "4656499" "4682414" "4696851" "4704626" "4707724" "4712161" "4725333" "4796083").PN.	USPAT	2004/02/26 20:32
-	10	("3702427" "4495378" "4577056" "4939316" "4967260" "5013871" "5025114" "5034591" "5132773" "5367196").PN.	USPAT	2004/02/26 20:35